

ELP 64/10/50 with I 64/5/50 Cores (without clamp recess)

Series/Type: B66295G, B66295K

Date: October 2022

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ELP 64/10/50

Core (without clamp recess)

B66295

Core set EELP 64

Combination: ELP 64/10/50 with ELP 64/10/50

■ To IEC 63093-9

■ Delivery mode: single units

Magnetic characteristics (per set)

 $\Sigma I/A = 0.15 \text{ mm}^{-1}$

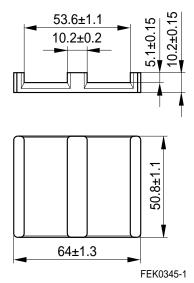
 $I_{e} = 79.9 \, \text{mm}$

 $A_e = 519 \text{ mm}^2$

 $A_{min} = 518 \text{ mm}^2$

 $V_e = 41500 \text{ mm}^3$

Approx. weight 210 g/set



ELP 64/10/50

Ungapped

Material	A _L value nH	μ_{e}	B _S mT	P _V W/set	Ordering code (per piece)
N49	8000 ±30%	980	250 ¹)	< 10.7 (50 mT, 500 kHz, 100 °C)	B66295G0000X149
N87	12500 ±25%	1490	3001)	< 5.5 (100 mT, 100 kHz, 100 °C)	B66295G0000X187
N97	12500 ±25%	1531	310 ¹⁾	< 4.2 (100 mT, 100 kHz, 100 °C)	B66295G0000X197
N95	15500 ±25%	1880	3201)	< 5.1 (100 mT, 100 kHz, 25 °C) < 4.2 (100 mT, 100 kHz, 100 °C)	B66295G0000X195

¹⁾ H = 250 A/m; f = 10 kHz; T = 100 °C

Other A_I values/air gaps and materials available on request – see Processing remarks on page 4.

Calculation factors (for formulas, see "E cores: general information") EELP 64:

Material	Relationship between air gap – A _L value		Calculation of saturation current				
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	820	-0.767	1280	-0.796	1182	-0.873	

Validity range: K1, K2: 0.10 mm < s < 2.00 mm

K3, K4: 480 nH < A_I < 4800 nH



ELP 64/10/50 with I 64/5/50

Core (without clamp recess)

B66295

Core set EILP 64 Combination:

ELP 64/10/50 with I 64/5/50

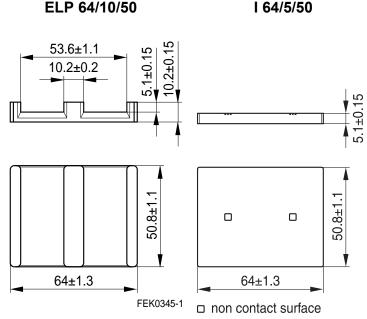
■ To IEC 63093-9

Delivery mode: single units

Magnetic characteristics (per set)

 Σ I/A = 0.13 mm⁻¹ I_e = 69.7 mm A_e = 519 mm² A_{min} = 518 mm² V_e = 36200 mm³

Approx. weight 185 g/set



FEK0593-X-E

Ungapped

Mate- rial	A _L value nH	μ _e	B _S mT	P _V W/set	Ordering code (per piece)
N49	8900 ±30%	950	250 ¹⁾	< 9.3 (50 mT, 500 kHz, 100 °C)	B66295G0000X149 (ELP core) B66295K0000X149 (I core)*
N87	14000 ±25%	1450	3001)	< 4.8 (100 mT, 100 kHz, 100 °C)	B66295G0000X187 (ELP core) B66295K0000X187 (I core)*

¹⁾ H = 250 A/m; f = 10 kHz; T = 100 °C

Other A_L values/air gaps and materials available on request – see Processing remarks on page 4.

Calculation factors (for formulas, see "E cores: general information") **EILP 64:**

Material	Relationship air gap – A _L v		Calculation of saturation current				
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	835	-0.790	1316	-0.796	1203	-0.873	

Validity range: K1, K2: 0.10 mm < s < 2.00 mm

K3, K4: 480 nH < A_L < 4800 nH

^{*} Plate-type tool



Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

Effects of core combination on A_I value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

Our ferrite accessories have been designed and evaluated only in combination with our ferrite cores. We explicitly point out that our ferrite accessories or our ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

We assume no warranty or reliability for the combination of our ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter "Processing notes", section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.



Cautions and warnings

Display of ordering codes for TDK Electronics products

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Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A_{e}	Effective magnetic cross section	mm ²
A_{L}	Inductance factor; $A_L = L/N^2$	nH
A_{L1}	Minimum inductance at defined high saturation ($\triangleq \mu_a$)	nH
A _{min}	Minimum core cross section	mm ²
A _N	Winding cross section	mm ²
A_R	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
В	RMS value of magnetic flux density	Vs/m ² , mT
ΔΒ	Flux density deviation	Vs/m ² , mT
Ê	Peak value of magnetic flux density	Vs/m ² , mT
Δ Ŝ	Peak value of flux density deviation	Vs/m ² , mT
B_{DC}	DC magnetic flux density	Vs/m ² , mT
B _R	Remanent flux density	Vs/m ² , mT
B _S	Saturation magnetization	Vs/m ² , mT
C_0	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
Ea	Activation energy	J
f	Frequency	s−1, Hz
f _{cutoff}	Cut-off frequency	s ⁻¹ , Hz
f _{max}	Upper frequency limit	s−1, Hz
f _{min}	Lower frequency limit	s ⁻¹ , Hz
f _r	Resonance frequency	s ^{−1} , Hz
f _{Cu}	Copper filling factor	
g	Air gap	mm
H	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H_{DC}	DC field strength	A/m
H _c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ⁻⁶ cm/A
h/μ_i^2	Relative hysteresis coefficient	10 ⁻⁶ cm/A
1	RMS value of current	Α
I _{DC}	Direct current	Α
Î	Peak value of current	A
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k ₃	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

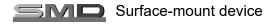
Symbol	Meaning	Unit
Δ L/L	Relative inductance change	Н
L_0	Inductance of coil without core	Н
L _H	Main inductance	Н
L_p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
L _s	Series inductance	Н
l _e	Effective magnetic path length	mm
I_N	Average length of turn	mm
N	Number of turns	
P_{Cu}	Copper (winding) losses	W
P _{trans}	Transferrable power	W
P _V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = $\omega L/R_s$ = 1/tan δ_l)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance (f = 0)	Ω
R _h	Hysteresis loss resistance of a core	Ω
ΔR_h	R _h change	Ω
R _i	Internal resistance	Ω
R_p	Parallel loss resistance of a core	Ω
R_s	Series loss resistance of a core	Ω
R _{th}	Thermal resistance	K/W
R _V	Effective loss resistance of a core	Ω
S	Total air gap	mm
Т	Temperature	°C
ΔT	Temperature difference	K
T_{C}	Curie temperature	°C
t	Time	s
t_v	Pulse duty factor	
tan δ	Loss factor	
tan δ_{l}	Loss factor of coil	
$tan \delta_r$	(Residual) loss factor at H \rightarrow 0	
$tan \delta_e$	Relative loss factor	
$tan \delta_h$	Hysteresis loss factor	
tan δ/μ_i	Relative loss factor of material at H \rightarrow 0	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V _e	Effective magnetic volume	mm ³
Z	Complex impedance	Ω
Z _n	Normalized impedance $ Z _n = Z / N^2 \times \varepsilon (I_e /A_e)$	Ω/mm



Symbols and terms

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_{F}	Relative temperature coefficient of material	1/K
α _e	Temperature coefficient of effective permeability	1/K
r	Relative permittivity	
Þ	Magnetic flux	Vs
1	Efficiency of a transformer	
В	Hysteresis material constant	mT-1
li	Hysteresis core constant	$A^{-1}H^{-1/2}$
'S	Magnetostriction at saturation magnetization	
,	Relative complex permeability	
0	Magnetic field constant	Vs/Am
a	Relative amplitude permeability	
app	Relative apparent permeability	
е	Relative effective permeability	
i	Relative initial permeability	
p'	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)	
p"	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)	
r	Relative permeability	
rev	Relative reversible permeability	
s'	Relative real (inductive) component of $\overline{\mu}$ (for series components)	
s S	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)	
tot	Relative total permeability	
	derived from the static magnetization curve	
	Resistivity	Ω m $^{-1}$
I/A	Magnetic form factor	mm ⁻¹
Cu	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
)	Angular frequency; ω = 2 Π f	s ⁻¹

All dimensions are given in mm.





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The following applies to all products named in this publication:

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- 3. The warnings, cautions and product-specific notes must be observed.
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